


TotalEnergies

Refining & Chemicals
Polymers

Polypropylene Lumicene® MR10YN9

Technical data sheet
Polypropylene – Metallocene Random Copolymer
Produced in Europe

Description

Lumicene® MR10YN9 is a metallocene random copolymer with a Melt Flow Index of 10 g/10 min for fiber extrusion. Lumicene® MR10YN9 offers an excellent softness and thermal bonding performance thanks to its low melting temperature. Thanks to the metallocene based technology, fibers produced with this resin show an exceptionally low level of volatile organic compounds (VOC).

Lumicene® MR10YN9 has a gas-fading resistant stabilization.

Characteristics

	Method	Unit	Typical Value
Rheological properties			
Melt Flow Index 230°C/2.16 kg	ISO 1133	g/10 min	10
Mechanical properties			
Flexural modulus	ISO 178	MPa	950
Thermal properties			
Melting Point	ISO 3146	°C	140
Other physical properties			
Density	ISO 1183	g/cm ³	0.902
Bulk Density	ISO 1183	g/cm ³	0.525

Handling and storage

Please refer to the safety data sheet (SDS) for handling and storage information. It is advisable to convert the product within one year after delivery provided storage conditions are used as given in the SDS of our product. SDS may be obtained from the website: www.polymers.totalenergies.com.

Polypropylene

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